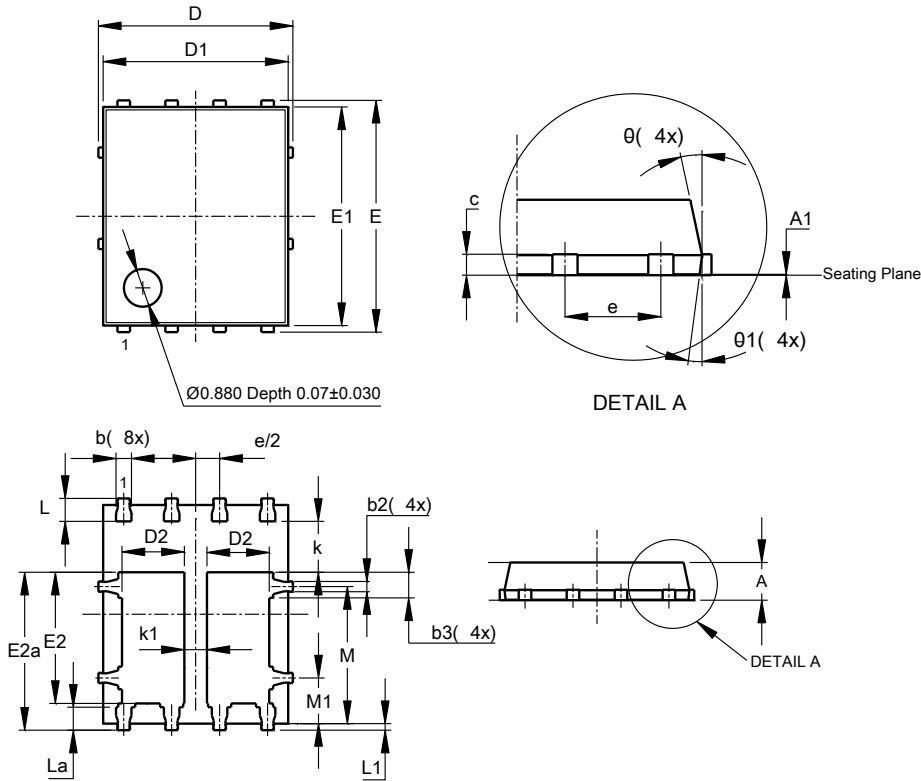


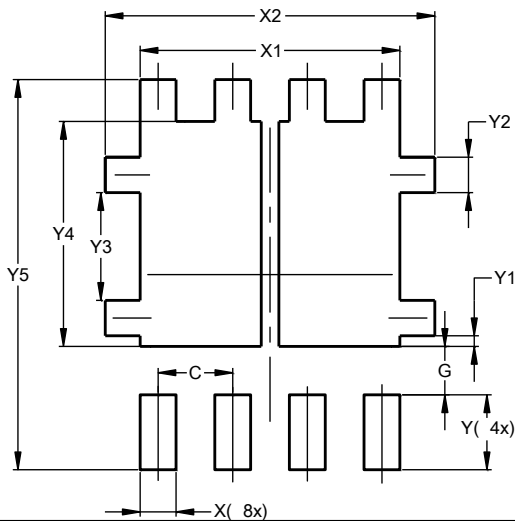
Package Outline Dimensions

PowerDI5060-8 (Type D)



PowerDI5060-8 (Type D)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	0.02
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.48	0.88	0.68
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	1.45	1.85	1.65
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E2a	3.99	4.39	4.19
e	1.27BSC		
k	0.51	-	-
k1	0.60 BSC		
L	0.51	0.71	0.61
La	0.51	0.71	0.61
L1	0.10	0.20	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	1.270
G	0.820
X	0.610
X1	4.420
X2	5.610
Y	1.270
Y1	0.180
Y2	0.600
Y3	1.825
Y4	3.810
Y5	6.610

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.